

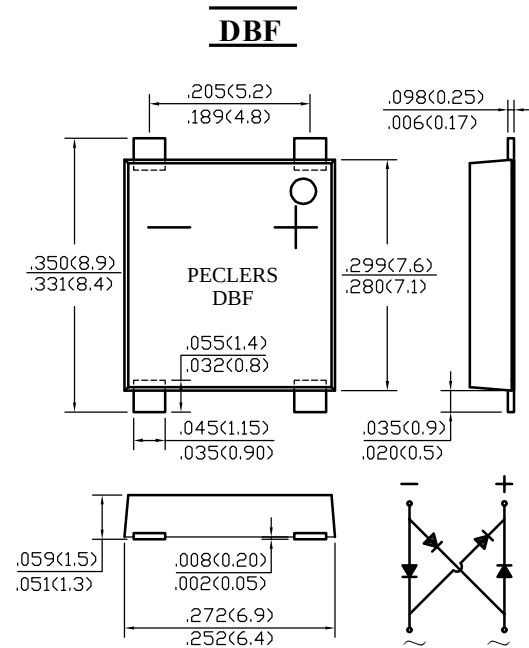
REVERSE VOLTAGE: 50 to 1000 VOLTS
FORWARD CURRENT: 6.0 AMPERE

FEATURE

- Glass passivated junction.
- Ideal for printed circuit board.
- Reliable low cost construction utilizing molded plastic technique.
- High surge current capability.
- High temperature soldering guaranteed: 260°C/10 seconds at terminals.

MECHANICAL DATA

- Case: Molded plastic, DBF
- Epoxy: UL 94V-O rate flame retardant
- Terminals: Leads solderable per MIL-STD-202, method 208 guaranteed
- Mounting position: Any
- Weight: 0.204g (approximately)



Dimensions in inches and (millimeters)

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25°C ambient temperature unless otherwise specified.

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%

Type Number	SYM BOL	RDBF 6005	RDBF 601	RDBF 602	RDBF 604	RDBF 606	RDBF 608	RDBF 610	units
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward rectified Current @ T _A =40°C	$I_{F(AV)}$	6.0							A
Peak Forward Surge Current 8.3ms single half sine-wave superimposed on rate load (JEDEC method)	I_{FSM}	100							A
Maximum Instantaneous Forward Voltage @I _F = 6.0A DC	V_F	1.3							V
Maximum DC Reverse Current @T _J =25°C at rated DC blocking voltage @T _J =125°C	I_R	5.0 500.0							μA
Maximum Reverse Recovery Time (Note 1)	trr	150				250	500		ns
Typical Thermal Resistance (Note2)	R_{JA}	15							°C /W
	R_{JC}	7							
Storage Temperature	T_{STG}	-55 to +150							°C
Operating Junction Temperature	T_J	-55 to +150							°C

Note:

1. Test Conditions: $I_F = 0.5\text{A}$, $I_R = -1.0\text{A}$, $I_{RR} = -0.25\text{A}$
2. Thermal resistance from Junction to case, lead and ambient in accordance with JESD-51.
Unit mounted on 15mm*12mm*1.6mm AL pad attach 195mm*195mm*10mm steel plate

RATINGS AND CHARACTERISTIC CURVES

FIG.1-TYPICAL FORWARD CURRENT DERATING CURVE

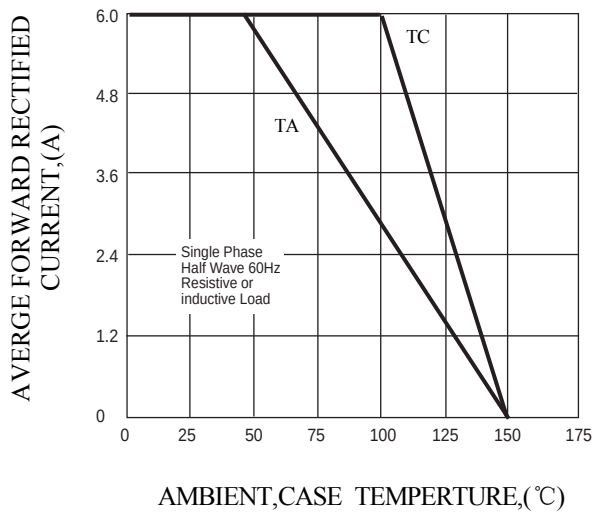


FIG.2-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

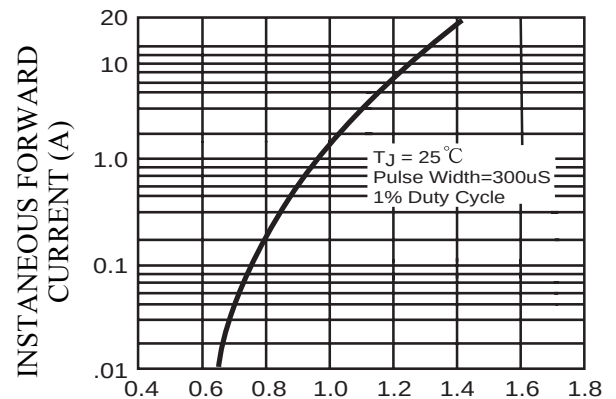


FIG.3-MAXIMUM NON-REPETITIVE FORWARD SURGE CURRENT

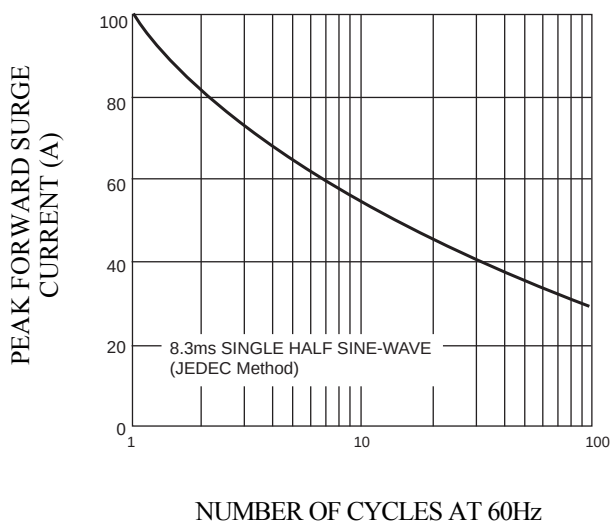


FIG.4-TYPICAL REVERSE CHARACTERISTICS

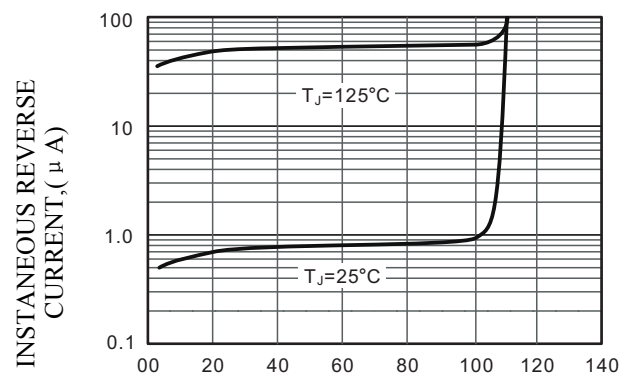


FIG. 5 - TEST CIRCUIT DIAGRAM AND REVERSE RECOVERY TIME CHARACTERISTIC

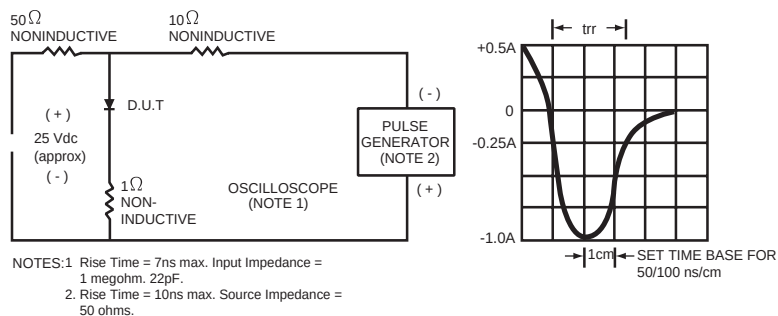


FIG.6 MOUNTING PAD LAYOUT

